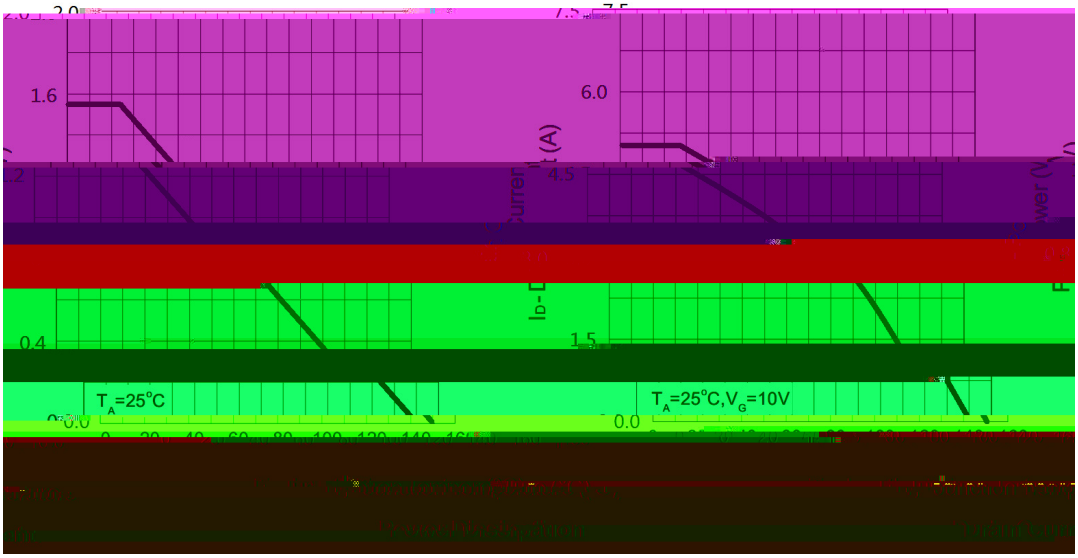
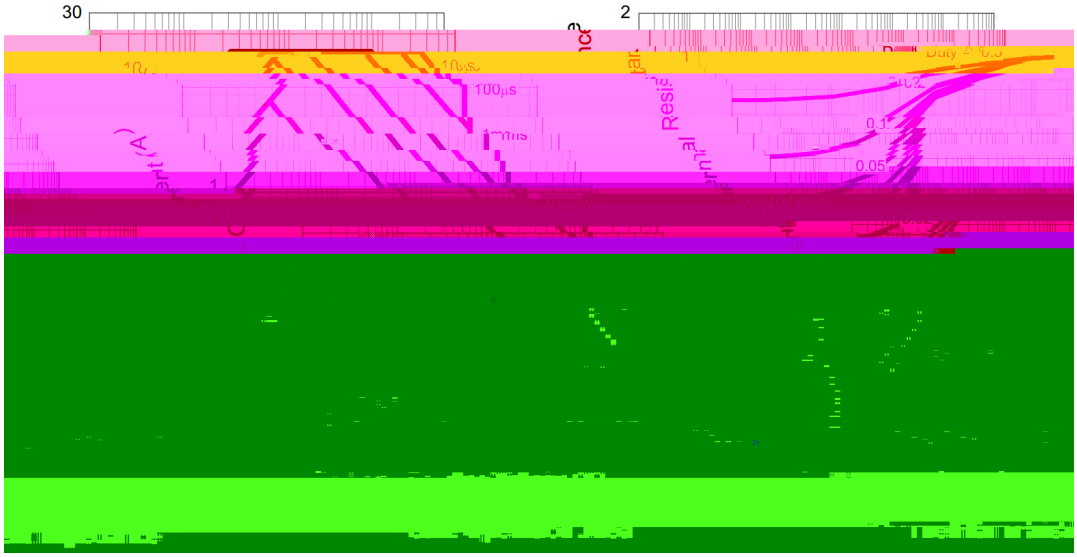
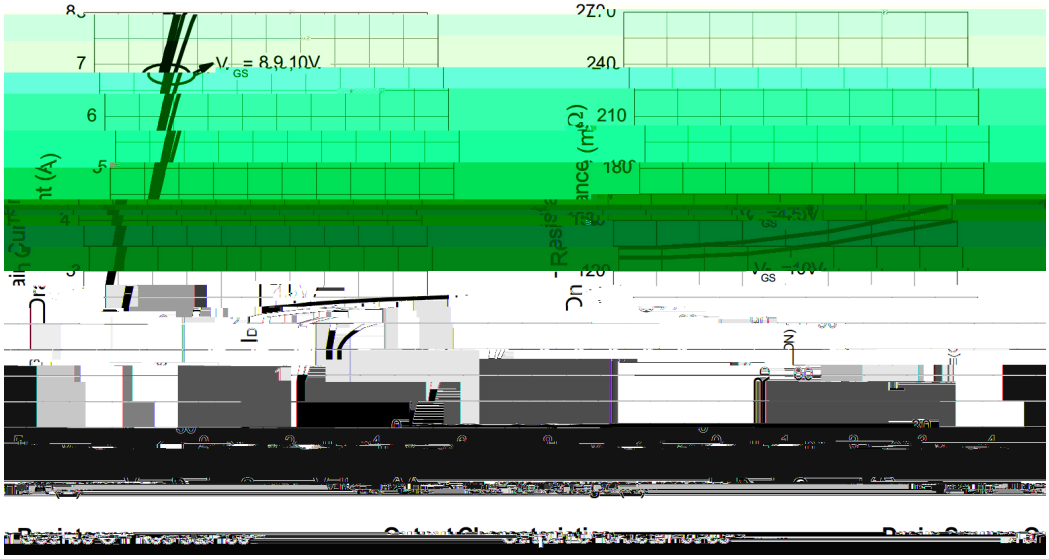
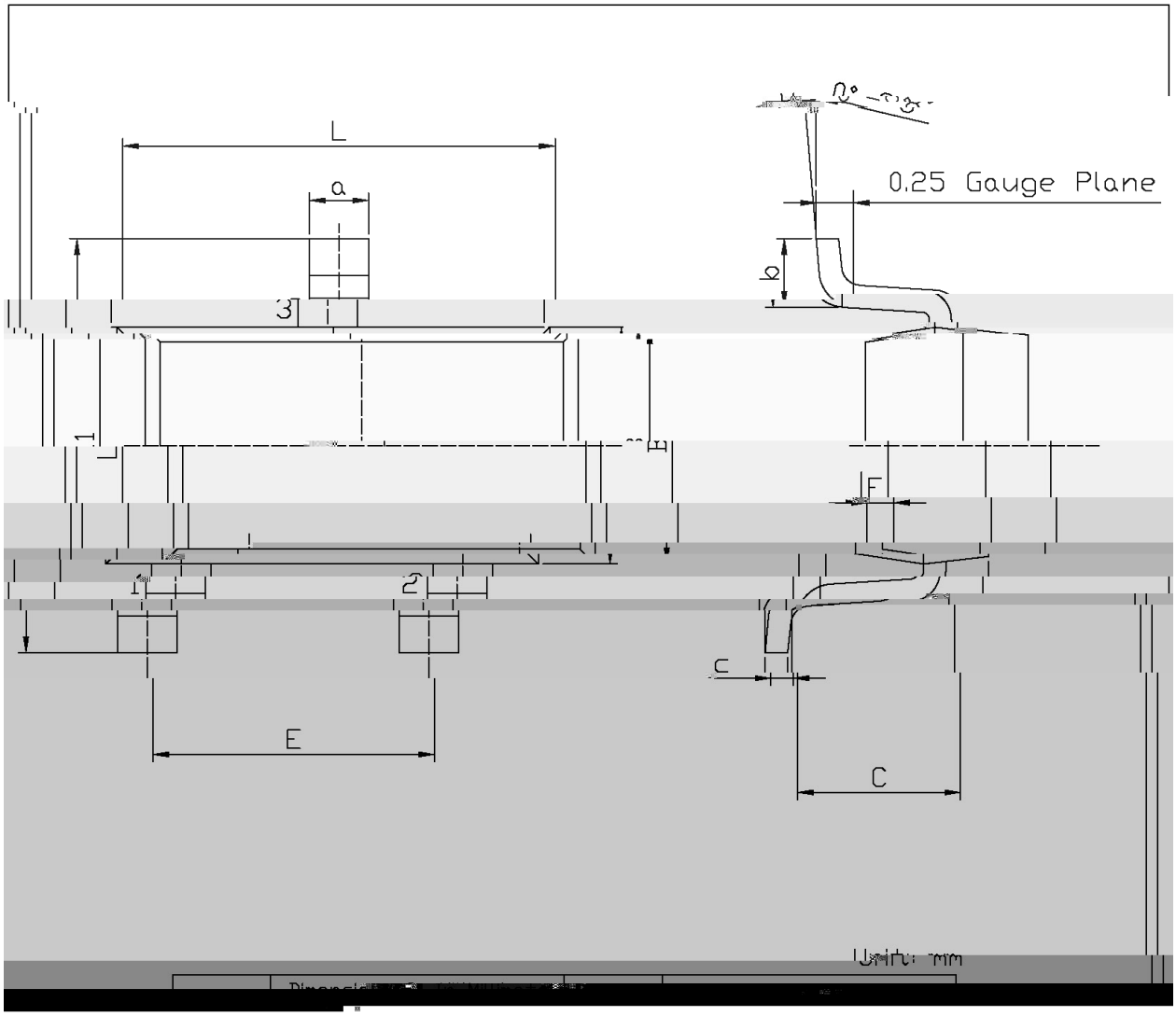
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	±20	V
Maximum Drain Current - Continuous	I_D	5.0	A
Drain Current- Pulsed	I_{DM}	15	A
Power Dissipation	P_D	1.55	W
Maximum Junction Temperature	T_J	150	
Storage Temperature Range	T_{STG}	-55 to 150	
Maximum Resistance –Junction to Ambient	R_{JA}	80.7	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_{DS}=250μA	100			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100V V_{GS}=0V			1	μA

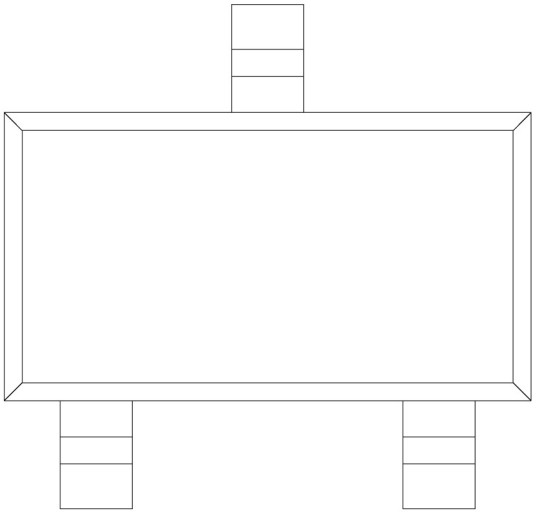

1.6
6.0
0.4
1.5
T_A=25°C
T_A=25°C,V_G=10V
0.0
0.0


30
2
100μs
1ms
0.1
0.05

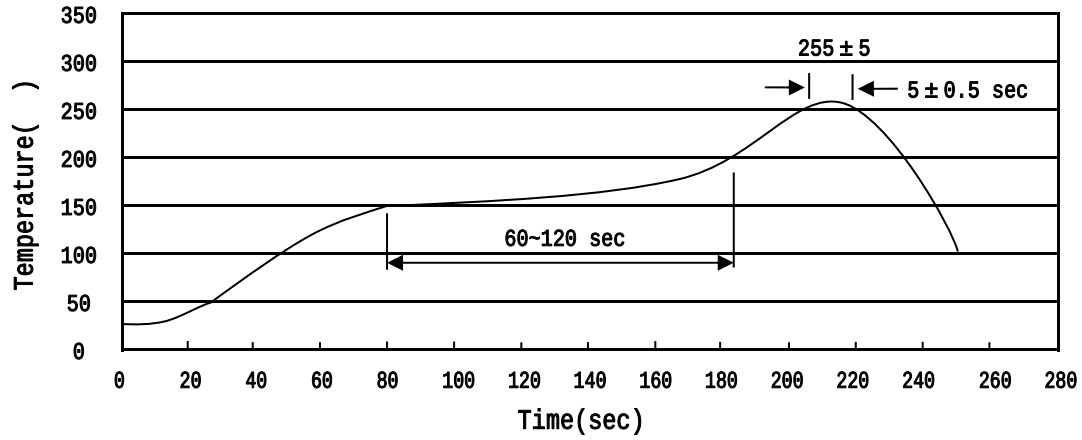

7
6
V_GS = 8,9,10V
240
210
180
V_GS 10V



SOT23-3



Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1		150	200		60	120sec;	1.Preheating:150~200 , Time:60~120sec.
2		255±5				5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3				2	10	/sec.	3.Cooling Speed: 2~10 /sec.

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT23-3	3,000	10	30,000	4	120,000	7 ×8	210×205×205	445×435×230